

### IN THE ABSTRACT

Page 10, delete the abstract in its entirety and substitute  
therefor the following:

--ABSTRACT OF THE DISCLOSURE

A method of providing a synthetic resin capping layer on a printed circuit in which the capping layer exhibits a variation of the mechanical properties in a direction at right angles to the capping layer. The capping layer is manufactured by injection moulding of a foam-forming injection-moulding material. This economically attractive method provides circuits which are well protected against mechanical and thermal stresses which may arise during operation. In addition, circuits having a synthetic resin capping layer can be used to reduce the thickness and the weight of portable devices, such as a mobile telephone.--